

STATEMENT UNDER 37 CFR 3.73(b)

Applicant/Patent Owner: Hui ZHONG, et al.

Application No./Patent No.: 10/049,270

Filed/Issue Date: June 27, 2002

Entitled: MULTILAYER PRINTED WIRING BOARD, SOLDER RESIST COMPOSITION, METHOD FOR
MANUFACTURING MULTILAYER PRINTED WIRING BOARD, AND SEMICONDUCTOR DEVICE

IBIDEN CO., LTD., a Corporation

(Name of Assignee)

(Type of Assignee, e.g., corporation, partnership, government agency, etc.)

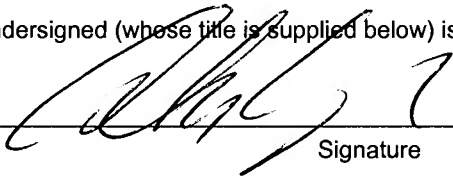
States that it is:

1. ☒ the assignee of the entire right, title, and interest; or
2. ☐ an assignee of less than the entire right, title and interest.

The extent (by, percentage) of its ownership interest is _____%

in the patent application/patent identified above by virtue of an assignment from the inventor(s) of the patent application/patent identified above. A copy of the assignment is attached. The assignment was previously recorded or is being recorded concurrently herewith.

The undersigned (whose title is supplied below) is authorized to act on behalf of the assignee.



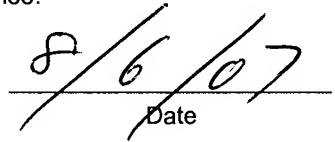
Signature

Akihiro Yamazaki

Printed or Typed Name

46,155

Registration Number



Date

703-413-3000

Telephone Number

COPY ONLY
NOT FOR RECORDATION

Assignment

Whereas, I/We, Hui ZHONG of c/o IBIDEN CO., LTD., 1-1, Kitagata, Ibigawacho, Ibi-gun, GIFU 501-0695 JAPAN; Kenichi SHIMADA of c/o IBIDEN CO., LTD., 1-1, Kitagata, Ibigawacho, Ibi-gun, GIFU 501-0695 JAPAN; Yukihiro TOYODA of c/o IBIDEN CO., LTD., 1-1, Kitagata, Ibigawacho, Ibi-gun, GIFU 501-0695 JAPAN; Motoo ASAI of c/o IBIDEN CO., LTD., 1-1, Kitagata, Ibigawacho, Ibi-gun, GIFU 501-0695 JAPAN; Dongdong WANG of c/o IBIDEN CO., LTD., 1-1, Kitagata, Ibigawacho, Ibi-gun, GIFU 501-0695 JAPAN; Koji SEKINE of c/o IBIDEN CO., LTD., 1-1, Kitagata, Ibigawacho, Ibi-gun, GIFU 501-0695 JAPAN; and Yoshitaka ONO of c/o IBIDEN CO., LTD., 1-1, Kitagata, Ibigawacho, Ibi-gun, GIFU 501-0695 JAPAN respectively, hereinafter called assignor(s), have invented certain improvements in MULTILAYERED PRINTED CIRCUIT BOARD, SOLDER RESIST COMPOSITION, MULTILAYERED PRINTED CIRCUIT BOARD MANUFACTURING METHOD, AND SEMICONDUCTOR DEVICE and executed an application for Letters Patent of the United States of America therefor on _____; and

Whereas, IBIDEN CO., LTD., 1, Kandacho 2-chome, Ogaki-shi, GIFU 503-0917 JAPAN (assignee), desires to acquire the entire right, title, and interest in the application and invention, and to any United States patents to be obtained therefor;

Now therefore, for valuable consideration, receipt whereof is hereby acknowledged,

I/We, the above named assignor(s), hereby sell, assign and transfer to the above named assignee, its successors and assigns, the entire right, title and interest in the application and the invention disclosed therein for the United States of America, including the right to claim priority under 35 U.S.C. §119, and I/we request the Director – U.S. Patent and Trademark Office to issue any Letters Patent granted upon the invention set forth in the application to the assignee, its successors and assigns; and I/we will execute without further consideration all papers deemed necessary by the assignee in connection with the United States application when called upon to do so by the assignee.

I/We hereby authorize and request our attorneys SUGHRUE MION, PLLC of 2100 Pennsylvania Avenue, NW, Washington, DC 20037-3213 to insert here in parentheses (Application number _____ and Confirmation number _____, filed _____) the filing date and application number of said application when known.

Date:	JUN. 18. 2002	Hui Zhong
		s/Hui ZHONG
Date:	JUN. 18. 2002	Ken-ichi Shimada
		s/Kenichi SHIMADA
Date:	JUN. 18. 2002	Yukihiro Toyoda
		s/Yukihiro TOYODA
Date:	JUN. 18. 2002	Motoo Asai
		s/Motoo ASAI
Date:	JUN. 18. 2002	Dongdong Wang
		s/Dongdong WANG
Date:	JUN. 18. 2002	Koji Sekine
		s/Koji SEKINE
Date:	JUN. 18. 2002	Yoshitaka Ono
		s/Yoshitaka ONO

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